



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-20
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M74HC132YRM13TR	IDK7*R132AAY	A	BO2A	2016-07-20
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6-3.9-1.52	14	gull wing	
Comment	Package: SO 14 .15 TO JEDEC MS-012			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDK7*R132AAY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.676	mg	supplier	die	Silicon (Si)	7440-21-3		1.634	mg	974940	12569
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	8353	108
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1193	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.026	mg	15513	200
Leadframe	Copper & its alloys	37.232	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.988	mg	966588	276831
				supplier	alloy	Iron (Fe)	7439-89-6		0.846	mg	22722	6508
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1370	392
				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1182	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.278	mg	7467	2138
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	242	69
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	215	62
supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	215	62				
Die attach	Other inorganic materials	0.361	mg	supplier	glue	Silver (Ag)	7440-22-4		0.305	mg	844875	2346
				supplier	glue	acrylate	Proprietary		0.017	mg	47091	131
				supplier	glue	Methacrylate	Proprietary		0.013	mg	36011	100
				supplier	glue	acrylate	Proprietary		0.013	mg	36011	100
				SVHC	glue	NMP	872-50-4		0.013	mg	36011	100
Bonding wire	Other inorganic materials	0.114	mg	supplier	wire	Copper (Cu)	7440-50-8		0.114	mg	1000000	877
encapsulation	Other inorganic materials	90.617	mg	supplier	mold compound	Silica, vitreous	60676-86-0		78.474	mg	865996	603646
				supplier	mold compound	Epoxy Resin	Proprietary		6.796	mg	74997	52277
				supplier	mold compound	Phenol Resin	Proprietary		4.531	mg	50002	34854
				supplier	mold compound	Carbon black	1333-86-4		0.453	mg	4999	3485
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.363	mg	4006	2792